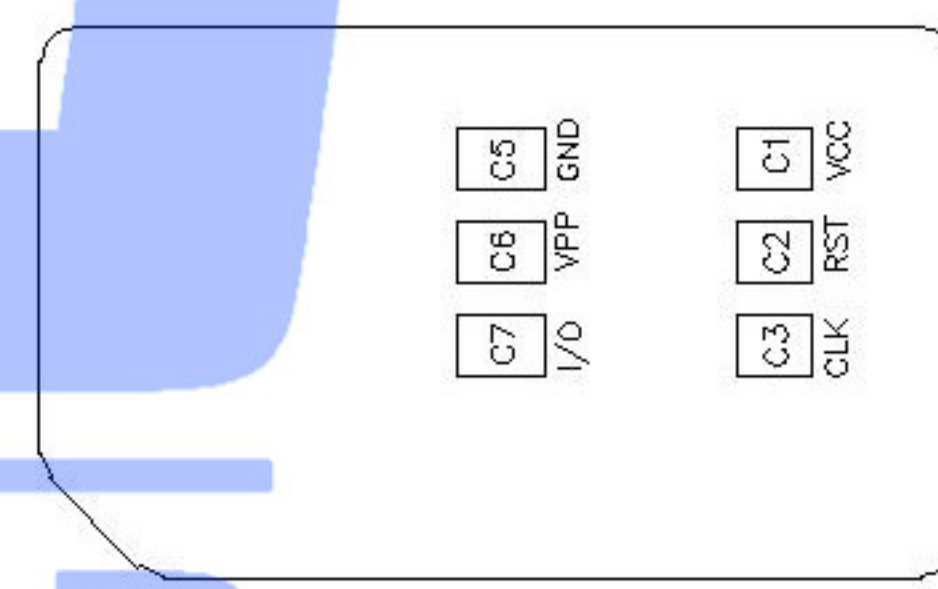
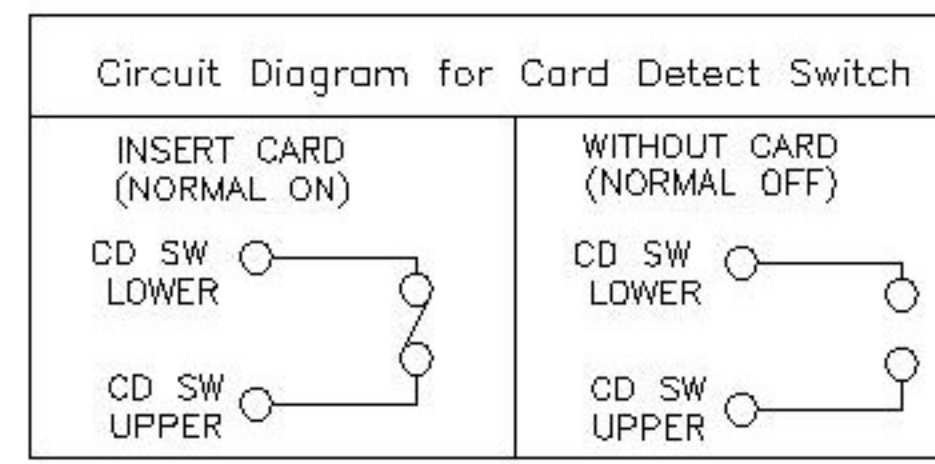
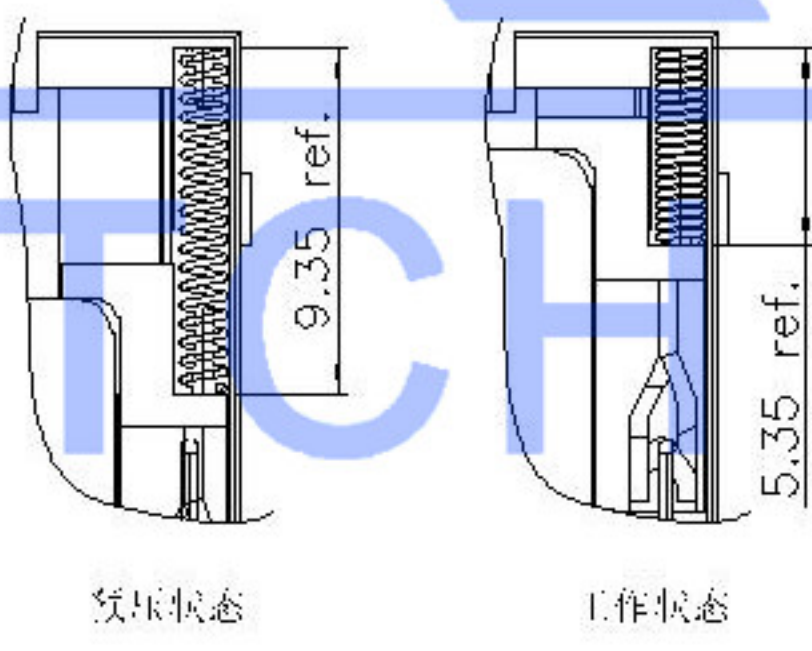


NOTES:
 1) MATERIAL:
 HOUSING: LCP UL 94V-0
 CONTACT: C5210R-H,T=0.15
 SHELL: SUS201,T=0.15
 MYLAR: POLYESTER
 2) FINISH :
 CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
 GOLD FLASH PLATING ON SOLDER TAILS, WITH
 ENTIRE CONTACT UNDERPLATED
 50u"Min,NICKEL
 SHELL: 50u"Min. NICKEL UNDERPLATED OVERALL ,
 GOLD FLASH PLATED ON SOLDER TAILS
 3) INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET



					DSND		DATE		SCALE: N/A	MODEL TYPE: SIM CARD CONN		
△X					ANGLAR	±5°	DWN	DATE	VIEW:	PART NO.:		
△X					L ≤ 4	±0.2	CHKD	DATE	UNIT: mm	DWG NO.:		
△X					4 < L ≤ 16	±0.3	APPD	DATE	SIZE: A4	XKSIM-115		
MARK	DESCRIPTION	DATE	REVISED	APPROVED	16 < L ≤ 63	±0.4				WEIGHT	SHEET	REVISION
					L > 63	±0.5				1.0g	1/1	A0
REVISIONS					UNSPECIFIED TOLERANCES			XKB INDUSTRIAL PRECISION CO., LIMITED				
www.xk-dg.cn www.helloxkb.com www.helloxkb.cn												